

IN THE SPECIFICATION:

Please amend paragraph number [0026] as follows:

[0026] An exemplary stereolithography apparatus useful in the present invention includes a fabrication tank in which a substrate(s) may be supported on a suitable platen or other support system, and upon which a structure(s) may be stereolithographically formed by irradiating or otherwise supplying energy to at least a surface of a quantity of consolidatable, unconsolidated material (*e.g.*, a photopolymer), thereby causing the material to become at least a least partially consolidated (*e.g.*, enter a semisolid state). The fabrication tank may include a reservoir that is configured to hold a volume of unconsolidated material, such as a liquid polymer.

Please amend paragraph number [0031] as follows:

[0031] In a stereolithography method for forming insulative coatings within via holes, a portion of the precursor hole is filled with a thin layer of unconsolidated material (*e.g.*, in liquid or particulate form), such as a flowable photopolymer, a resin-covered particulate material, or another suitable unconsolidated material. The precursor hole is filled to a predetermined depth with the unconsolidated material, forming a layer which may have a thickness of from ~~about 2 μ m~~ about 2 μ m to about 75 μ m and having an upper surface. The layer may be formed by immersing the substrate in a quantity of unconsolidated material, by injecting a controlled volume of the unconsolidated material into the hole from above, or by other suitable techniques.

Please amend paragraph number [0065] as follows:

[0065] An example of the manner in which portions of unconsolidated material 78 may be at least partially consolidated is illustrated in exemplary FIG. 8. Portions of upper surfaces 128A of unconsolidated material 78 in precursor holes 70 of substrate 60 are irradiated with a movable laser beam 220A to at least partially consolidate unconsolidated material 78 into an at least semisolid state, thereby forming a layer 80A of each insulative coating 80. The movement of laser beam 220A may be controlled by controller 700 (see FIG. 4) to impart

layer 80A with a desired shape (*e.g.*, cylindrical, frustoconical, etc.). A nonirradiated portion in each layer 80A of each insulative coating 80 comprises a portion 90A of a corresponding via hole 90 (*see* FIG. 12), which is initially filled with unconsolidated material 78.

Please amend paragraph number [0087] as follows:

[0087] FIGs. 6, 6A, and 14 depict yet another exemplary type of support element 134". In this embodiment, a step 96 encircles the inside of the peripheral edge 92 for supporting the edge of a substrate 60, such as a wafer 61. As supported, the substrate 60 is spaced from the perforated support surface 150. One or more perforations 148 permit flow of unconsolidated material 78 into the lower ends 86 of the precursor holes 70 and subsequently into the lower openings of the via holes 90 (FIG. 12). The desired level 128 of volume 124 of unconsolidated material 78 may be achieved by either moving the material level 128 upward (adding unconsolidated material 78 to fabrication tank 100) or displacing unconsolidated material 78 within fabrication tank 100 by submersing the support element ~~134~~ 134" and attached substrate 60 downward into the unconsolidated material 78, or by a combination of the foregoing techniques.

Please amend paragraph number [0091] as follows:

[0091] Alternatively, as shown in FIG. 4A, a surface level control element 154' may include one or more apertures or other openings 102 in a side wall 101 of tank 100' that have lower edges 103 that are positioned at an elevation within tank 100' at which surface 128 of volume 124 of unconsolidated material 78 is to be maintained. In addition, surface level control element 154' includes one or more receptacles 104 that communicate with openings 102 to receive overflowing unconsolidated material 78 as support element 134 and a workpiece, if any, thereon, as well as ~~stereolithographically~~ stereolithographically fabricated objects, are lowered into tank 100' and displace unconsolidated material 78 therein. A pumping system or other material recycling element 105 may communicate with each receptacle 104 in such a way as to return overflowed unconsolidated material 78 to tank 100' as support element 134 is raised to facilitate stereolithographic fabrication of one or more other objects.